

$512 \times 9 \& 1 K \times 9 CMOS$ Parallel FIFO

Introduction

The M67201A/202A implement a first-in first-out algorithm, featuring asynchronous read/write operations. The FULL and EMPTY flags prevent data overflow and underflow. The Expansion logic allows unlimited expansion in word size and depth with no timing penalties. Twin address pointers automatically generate internal read and write addresses, and no external address information are required for the TEMIC FIFOs. Address pointers are automatically incremented with the write pin and read pin. The 9 bits wide data are used in data communications applications where a parity bit for error checking is necessary. The Retransmit pin reset the Read pointer to zero without affecting the write pointer. This is very useful for retransmitting data when an error is detected in the system.

Using an array of eigh transistors (8 T) memory cell and fabricated with the state of the art 1.0 μ m lithography named SCMOS, the M 67201A/202A combine an extremely low standby supply current (typ = 1.0 μ A) with a fast access time at 25 ns over the full temperature range. All versions offer battery backup data retention capability with a typical power consumption at less than 5 μ W.

For military/space applications that demand superior levels of performance and reliability the M 67201A/202A is processed according to the methods of the latest revision of the MIL STD 883 (class B or S) and/or ESA SCC 9000.

Features

- · First-in first-out dual port memory
- 512 × 9 organisation (M 67201A)
- 1024 × 9 organisation (M 67202A)
- · Fast access time

20*, 25, 35, 45, 55 ns, commercial, industrial and automotive

20*, 25, 30, 40, 50 ns, military

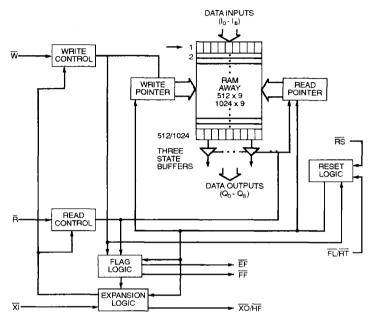
- Wide temperature range : - 55°C to + 125°C
- 67201AL/202AL fow power 67201AV/202AV very low
 power
- · Fully expandable by word width or depth
- * Preview. Please Consult Sales.

- · Asynchronous read/write operations
- Empty, full and half flags in single device mode
- · Retransmit capability
- Bi-directional applications
- · Battery back-up operation : 2 V data retention
- TTL compatible
- Single 5 V ± 10 % Power Supply (1)
- High performance SCMOS technology

(1) 3.3 V versions are also available. Please consult sales.

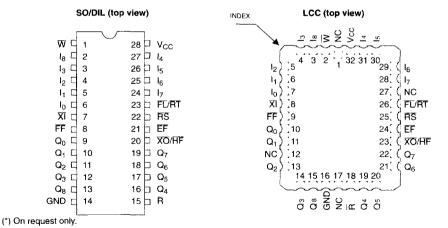
Interface

Block Diagram



Pin Configuration

SO plastic 28 pin 300 mils(*) DIL plastic 28 pin 300 mils DIL ceramic 28 pin 300 mils FP 28 pin 400 mils (Preview) 32 pin LCC and PLCC



M67201A/M67202A

Pin Names

NAMES	DESCRIPTION
IO-8	Inputs
Q0-8	Outputs
W	Write Enable
R	Read Enable
RS	Reset
EF	Empty Flag

NAMES	DESCRIPTION
FF	Full Flag
XO/HF	Expansion Out/Half-Full Flag
Xi	Expansion IN
FL/RT	First Load/Retransmit
VCC	Power Supply
GND	Ground

Signal Description

Data In (10 - 18)

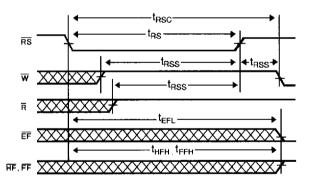
Data inputs for 9 - bit data

RESET (RS)

Reset occurs whenever the Reset (\overline{RS}) input is taken to a low state. Reset returns both internal read and write

pointers to the first location. A reset is required after power-up before a write operation can be enabled. Both the Read Enable (\overline{R}) and Write Enable (\overline{W}) inputs must be in the high state during the period shown in figure 1 (i.e. t_{RSS} before the rising edge of \overline{RS}) and should not change until t_{RSR} after the rising edge of \overline{RS} . The Half-Full flag (\overline{HF}) will be reset to high after Reset (\overline{RS}) .

Figure 1. Reset.



Notes: 1. \overline{EF} , \overline{FF} and \overline{HF} may change status during reset, but flags will be valid at t_{RSC} .

2. \overline{W} and $\overline{R} = VIH$ around the rising edge of RS.

Write Enable $(\overline{\overline{W}})$

A write cycle is initiated on the falling edge of this input if the Full Flag (\overline{FF}) is not set. Data set-up and hold times must be maintained in the rise time of the leading edge of the Write Enable (\overline{W}). Data is stored sequentially in the Ram array, regardless of any current read operation.

Once half of the mernory is filled, and during the falling edge of the next write operation, the Half-Full Flag (\overline{HF}) will be set to low and remain in this state until the difference between the write and read pointers is less than

or equal to half of the total available memory in the device. The Half-Full Flag (\overline{HF}) is then reset by the rising edge of the read operation.

To prevent data overflow, the Full Flag (\overline{FF}) will go low, inhibiting further write operations. On completion of a valid read operation, the Full Flag (\overline{FF}) will go high after TRFF, allowing a valid write to begin. When the FIFO stack is full, the internal write pointer is blocked from \overline{W} , so that external changes to \overline{W} will have no effect on the full FIFO stack.

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Read Enable (R)

A read cycle is initiated on the falling edge of the Read Enable (\overline{R}) provided that the Empty Flag (\overline{EF}) is not set. The data is accessed on a first in/first out basis, not with standing any current write operations. After Read Enable (\overline{R}) goes high, the Data Outputs (Q0 - Q8) will return to a high impedance state until the next Read operation. When all the data in the FIFO stack has been read, the Empty Flag (\overline{EF}) will go low, allowing the "final" read cycle, but inhibiting further read operations whilst the data outputs remain in a high impedance state. Once a valid write operation has been completed, the Empty Flag (\overline{EF}) will go high after tWEF and a valid read may then be initiated. When the FIFO stack is empty, the internal read pointer is blocked from \overline{R} , so that external changes to \overline{R} will have no effect on the empty FIFO stack.

First Load/Retransmit (FL/RT)

This is a dual-purpose input. In the Depth Expansion Mode, this pin is connected to ground to indicate that it is the first loaded (see Operating Modes). In the Single Device Mode, this pin acts as the retransmit input. The Single Device Mode is initiated by connecting the Expansion In (\overline{XI}) to ground.

The M 67201A/202A can be made to retransmit data when the Retransmit Enable Control (\overline{RT}) input is pulsed low. A retransmit operation will set the internal read point to the first location and will not affect the write pointer. Read Enable (\overline{R}) and Write Enable (\overline{W}) must be in the high state during retransmit. The retransmit feature is intended for use when a number of writes equals to or less than the depth of the FIFO have occured since the last \overline{RS} cycle. The retransmit feature is not compatible with the Depth Expansion Mode and will affect the Half-Full Flag (\overline{HF}), in accordance with the relative locations of the read and write pointers.

Expansion In (\overline{XI})

This input is a dual-purpose pin. Expansion In (\overline{XI}) is connected to GND to indicate an operation in the single device mode. Expansion In (\overline{XI}) is connected to Expansion Out (\overline{XO}) of the previous device in the Depth Expansion or Daisy Chain modes.

Full Flag (FF)

The Full Flag (\overline{FF}) will go low, inhibiting further write operations when the write pointer is one location less than the read pointer, indicating that the device is full. If the read pointer is not moved after Reset (\overline{RS}), the Full Flag (\overline{FF}) will go low after 512/1024 writes.

Empty Flag (EF)

The Empty Flag (EF) will go low, inhibiting further read operations when the read pointer is equal to the write pointer, indicating that the device is empty.

Expansion Out/Half-full Flag (XO/HF)

This is a dual-purpose output. In the single device mode, when Expansion In (\overline{XI}) is connected to ground, this output acts as an indication of a half-full memory.

After half the memory is filled and on the falling edge of the next write operation, the Half-Full Flag (HF) will be set to low and will remain set until the difference between the write and read pointers is less than or equal to half of the total memory of the device. The Half-Full Flag (HF) is then reset by the rising edge of the read operation.

In the Depth Expansion Mode, Expansion In (\overline{XI}) is connected to Expansion Out (\overline{XO}) of the previous device. This output acts as a signal to the next device in the Daisy Chain by providing a pulse to the next device when the previous device reaches the last memory location.

Data Output $(Q_0 - Q_8)$

DATA output for 9-bit wide data. This data is in a high impedance condition whenever Read (R) is in a high state.



Functional Description

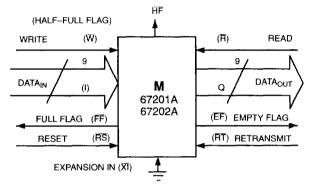
Operating Modes

Single Device Mode

A single M 67201A/202A may be used when the application requirements are for 512/1024 words or less.

The M 67201A/202A is in a Single Device Configuration when the Expansion In (\overline{XI}) control input is grounded (see Figure 2). In this mode the Half-Full Flag (\overline{HF}) , which is an active low output, is shared with Expansion Out (\overline{XO}) .

Figure 2. Block Diagram of Single 512×9 and 1024×9 .

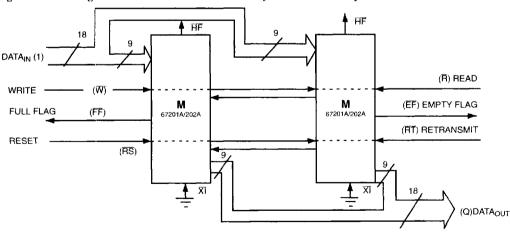


WIDTH EXPANSION MODE

Word width may be increased simply by connecting the corresponding input control signals of multiple devices.

Status flags (EF, FF and HF) can be detected from any device. Figure 3 demonstrates an 18-bit word width by using two M 67201A/202A. Any word width can be attained by adding additional M 67201A/202A.

Figure 3. Block Diagram of 512 / 1024 × 18 FIFO Memory Used in Width Expansion Mode.



Note: 3. Flag detection is accomplished by monitoring the FF. EF and the HF signals on either (any) device used in the width expansion configuration. Do not connect any output control signals together.

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Table 1: Reset and retransmit Single Device Configuration/Width Expansion Mode

		INPUTS		INTERNA	L STATUS		OUTPUT	Ś
MODE	RS	RT	XI	Read Pointer	Write Pointer	TF	PF	HF .
Reset	0	х	0	Location Zero	Location Zero	0	1	1
Retransmit	1	0	0	Location Zero	Unchanged	Х	Х	X
Read/Write	1	ı	0	Increment(4)	Increment(4)	Х	Х	Х

Note: 4. Pointer will increment if flag is high.

Table 2: Reset and First Load Truth Table
Depth Expansion/Compound Expansion Mode

		INPUTS		INTERNA	L STATUS	oum	PUTS
MODE	RS	H	XI	Read Pointer	Write Pointer	EF	FF
Reset First Device	0	0	(5)	Location Zero	Location Zero	0	1
Reset All Other Devices	0	1	(5)	Location Zero	Location Zero	0	1
Read/Write	I	Х	(5)	X	X	х	Х

Note: 5. \overline{XI} is connected to \overline{XO} of previous device. See fig. 5.

Depth Expansion (Daisy Chain) Mode

The M 67201A/202A can be easily adapted for applications which require more than 512/1024 words. Figure 4 demonstrates Depth Expansion using three M 67201A/202A. Any depth can be achieved by adding additional 67201A/202A.

The M 67201A/202A operate in the Depth Expansion configuration if the following conditions are met:

- The first device must be designated by connecting the First Load (FL) control input to ground.
- 2. All other devices must have FL in the high state.
- The Expansion Out (XO) pin of each device must be connected to the Expansion In (XI) pin of the next device. See figure 4.
- 4. External logic is needed to generate a composite Full Flag (FF) and Empty Flag (EF). This requires that all EF's and all FFs be ØRed (i.e. all must be set to generate the correct composite FF or EF). See figure 4.
- 5. The Retransmit (RT) function and Half-Full Flag (HF) are not available in the Depth Expansion Mode.

Compound Expansion Module

It is quite simple to apply the two expansion techniques described above together to create large FIFO arrays (see figure 5).

Bidirectional Mode

Applications which require data buffering between two systems (each system being capable of Read and Write operations) can be created by coupling M 67201A/202A as shown in figure 6. Care must be taken to ensure that the appropriate flag is monitored by each system (i.e. \overline{FF} is monitored on the device on which \overline{W} is in use; \overline{EF} is monitored on the device on which \overline{R} is in use). Both Depth Expansion and Width Expansion may be used in this mode.

Data Flow - Through Modes

Two types of flow-through modes are permitted: a read flow-through and a write flow-through mode. In the read flow-through mode (figure 17) the FIFO stack allows a

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single word to be read after one word has been written to an empty FIFO stack. The data is enabled on the bus at (tWEF + tA) ns after the leading edge of \overline{W} which is known as the first write edge and remains on the bus until the \overline{R} line is raised from low to high, after which the bus will go into a three-state mode after tRHZ ns. The \overline{EF} line will show a pulse indicating temporary reset and then will be set. In the interval in which \overline{R} is low, more words may be written to the FIFO stack (the subsequent writes after the first write edge will reset the Empty Flag) ; however, the same word (written on the first write edge) presented to the output bus as the read pointer will not be incremented if \overline{R} is low. On toggling \overline{R} , the remaining words written to the FIFO will appear on the output bus in accordance with the read cycle timings.

In the write flow-through mode (figure 18), the FIFO stack allows a single word of data to be written immediately after a single word of data has been read from a full FIFO stack. The \overline{R} line causes the \overline{FF} to be reset, but the \overline{W} line, being low, causes it to be set again in anticipation of a new data word. The new word is loaded into the FIFO stack on the leading edge of \overline{W} . The \overline{W} line must be toggled when \overline{FF} is not set in order to write new data into the FIFO stack and to increment the write pointer.

Figure 4. Block Diagram of 1536 × 9 / 3072 × 9 FIFO Memory (Depth expansion).

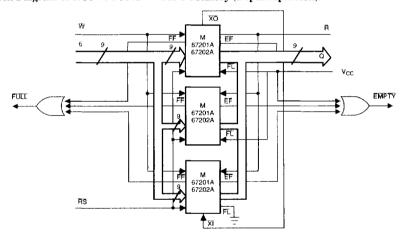
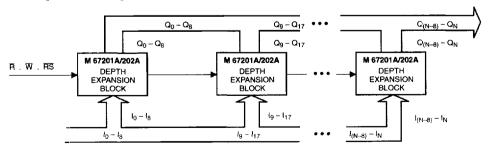


Figure 5. Compound FIFO Expansion.

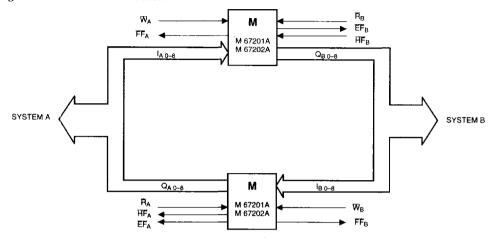


Notes: 6. For depth expansion block see section on Depth Expansion and Figure 4.

^{7.} For Flag detection see section on Width Expansion and Figure 3.



Figure 6. Bidirectional FIFO Mode.



Electrical Characteristics

Absolute Maximum Ratings

OPERATING RANGE	OPERATING SUPPLY VOLTAGE	OPERATING TEMPERATURE
Military	$Vcc = 5 V \pm 10 \%$	- 55 °C to + 125 °C
Industrial	$Vcc = 5 V \pm 10 \%$	- 40 °C to + 85 °C
Commercial	Vcc = 5 V ± 10 %	0 °C to + 70 °C
Automotive	$Vcc = 5 V \pm 10 \%$	- 40 °C to + 125 °C

DC Parameters

			M 67	201A 202A		201A 202A	M 67201A M 67202A	A	'201A '202A		
	en a la julio partiro.		- 20 (P	- 20 (Preview)		25	-30	- 35			
			сом	IND MIL AUTO	сом	IND MIL AUTO	MIL	сом	IND AUTO	UNIT	VAL- UE
JCCOP (8)	Operating	v	140	150	125	140	140	120	140	mA	Max
	supply current	L	140	150	125	140	140	120	140	mA	Max
I _{CCSB (9)}	Standby	V	1.5	1.5	1.5	1.5	1.5	1.5	1.5	mA	Max
	supply current	L	1.5	1.5	1.5	1.5	1.5	1.5	1.5	mA	Max
I _{CCPD (10)}	Power down	V	40	80	40	80	80	40	80	μΑ	Max
	current	L	400	800	400	800	800	400	800	μA	Max



DC Parameters (continued)

			M 67201A M 67202A -40	M 6	201A 202A	M 67201A M 67202A	M 67	201A 202A 55		
Parameter	Description	Version	MIL	-45 -50 COM IND MIL			сом	IND AUTO	UNIT	VAL- UE
I _{CCOP (8)}	Operating	V	120	80	120	100	70	100	mA	Max
	supply current	L	120	80	120	100	70	100	mA	Max
I _{CCSB (9)}	Standby	V	1.5	1.5	1.5	1.5	1.5	1.5	mA	Max
	supply current	L	1.5	1.5	1.5	1.5	1.5	1.5	mA	Max
I _{CCPD (10)}	Power down	V	80	40	80	80	40	80	μА	Max
	current	L	800	400	800	800	400	800	μА	Max

Notes: 8. Icc measurements are made with outputs open. F = F max

9. $\overline{R} = \overline{W} = \overline{RS} = \overline{FL/RT} = VIH$.

10. All input = Vcc.

		M 672	01A/M672 0 2A		J.
PARAMETER	DESCRIPTION	- 20/- 25/- 30/	- 35/- 40/- 45/- 50/- 55	UNIT	VALUE
ILI (11)	Input leakage current	±Ι	±1	uА	Max
ILO (12)	Output leakage current	± 10	± 10	uΑ	Max
VIL (13)	Input low voltage	0.8	0.8	V	Max
VIH (13)	Input high voltage	2.2	2.2	V	Min
VOL (14)	Output low voltage	0.4	0.4	V	Max
VOH (14)	Output high voltage	2.4	2.4	V	Min
C IN (15)	Input capacitance	8	8	рF	Max
C OUT (15)	Output capacitance	8	8	рF	Max

Notes: 11. $0.4 \le Vin \le Vcc$.

12. $\overline{R} = VIH$, $0.4 \le VOUT \le VCC$.

13. VIH max = Vec + 0.3 V. VIL min = -0.3 V or -1 V pulse width 50 ns.

14. Vec min, IOL = 8 mA, IOH = -2 mA.

15. This parameter is sampled and not tested 100 % – TA = 25 °C – F = 1 MHz.

AC Test Conditions

Figure 7. Output Load.

Input pulse levels : Gnd to 3.0 V
Input rise/Fall times : 5 ns
Input timing reference levels : 1.5 VOutput reference levels : 1.5 VOutput load : See figure 7

1.259



SYMBOL (16)	SYMBOL (17)	PARAMETER (18) (22)	COM MIL,	1A/202A L, IND, AUTO 20	COM MIL,	1A/202A , IND, AUTO 25	MIL.	1A/202A ONLY 30	COM AU	1A/282A I, IND, UTO 35	UNIT
			MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
READ CYC	LE		PRE	VIEW							*********
TRLRL	tRC	Read cycle time	30	-	35	-	40		45	-	ns
TRLQV	tA	Access time	-	20	-	25		30		35	ns
TRHRL	ıRR	Read recovery time	10		10	1 -	10	-	10	-	ns
TRLRH	tRPW	Read pulse width (19)	20		25		30		35	_	ns
TRLQX	tRLZ.	Read low to data low Z (20)	5	-	5	-	5	-	5	-	ns
TWHQX	tWLZ	Write low to data low Z (20, 21)	5	-	5		10	-	10		ns
TRHQX	tDV	Data valid from read high	5		5	-	5		5	-	ns
TRHQZ	tRHZ	Read high to data high Z (20)	-	15		18	_	20	_	20	ns
WRITE CYC	CLE		PRE	VIEW		f			1		
TWLWL	tWC	Write cycle time	30	_	35		40	_	45		ns
TWLWH	tWPW	Write pulse width (19)	20		25		30	T -	35		ns
TWHWL	tWR	Write recovery time	10	-	10		10	-	10		ns
TDVWH	tDS	Data set-up time	12		15	_	18		18		ns
TWHDX	tDH	Data hold time	0		0	_	0	_	()	_	ns
RESET CYC	CLE	I	PRE	VIEW		<u> </u>	İ			 	
TRSLWL	tRSC	Reset cycle time	30		35		40	_	45		ns
TRSLRSH	tRS	Reset pulse width (19)	20	-	25	-	30	l	35	-	ns
TWHRSH	tRSS	Reset set-up time	20		25	-	30	-	35	-	ns
TRSHWL	tRSR	Reset recovery time	10	_	10	-	10	1	10	 -	ns
RETRANSM	IIT CYCLE	J.,	PRE	VIEW		 					
TRTLWL	tRTC	Retransmit cycle time	30		35		40		45	l -	ns
TRTLRTH	tRT	Retransmit pulse width (19)	20	<u> </u>	25	_	30		35	†	ns
TWHRTH	tRTS	Retransmit setup time (20)	20		25	-	30	_	35	-	ns
TRTHWL	tRTR	Retransmit recovery time	10	-	10	T -	10		10	-	ns
FLAGS	J		PRE	VIEW		ļ		†	<u> </u>	-	
TRSLEFL	tEFL	Reset to EF low	_	30	_	35		40		45	ns
TRSLFFH	tHFH, tFFH	Reset to HF/FF high		30	_	35		40	-	45	ns
TRLEFL	tREF	Read low to EF low	_	20		25		30	:	30	ns
TRHFFH	tRFF	Read high to FF high	<u> </u>	20	-	25		30		30	ns
TEFHRH	tRPE	Read width after EF high	20	 -	25		30	-	35	_	ns
TWHEFH	tWEF	Write high to EF high	-	20	-	25	-	30	-	30	ns
TWLFFL	tWFF	Write low to FF low		20		25		30	 	30	ns
TWLHFL	tWHF	Write low to HF low	 -	30	-	35		40	-	45	ns
TRHHFH	tRHF	Read high to HF high	†	30	<u> </u>	35		40	<u> </u>	45	ns
TFFHWH	tWPF	Write width after FF high	20	1 -	25	1 -	30		35	-	ns

TEMIC

M67201A/M67202A

SYMBOL SYMBOL (16) (17)		PARAMETER (18) (22)				i, IND. AUTO	MIL	1A/202A ONLY 50	M 67201A/202A COM, IND, AUTO - 55		UNIT
			MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
READ CYC	LE		**********	30 A-210-07-0	S. C. WELLEY ST.	*E-19 20-60-20-21-19	Ser, les us, hu	14 2 4 4 1 4 1 4 1 4 1 4 1 4 1 4 1 4 1 4	5.540 ASSESSOR	(2) A 10(1) (1) A 10(1)	Paragraphen (
TRLRL	tRC	Read cycle time	50	-	55	-	65		70	_	ns
TRLQV	tA	Access time	-	40	-	45	_	50		55	ns
TRHRL	tRR	Read recovery time	10	-	10	_	15		15	_	ns
TRLRH	tRPW	Read pulse width (19)	40		45	_	50		55		ns
TRLQX	tRLZ	Read low to data low Z (20)	5	_	5	-	10	_	10	_	ns
TWHQX	tWLZ	Write low to data low Z (20, 21)	10		10	-	15	_	15	**	ns
TRHQX	tDV	Data valid from read high	5		5	-	5	-	5	-	ns
TRHQZ	tRHZ	Read high to data high Z (20)	-	25		25	-	30	_	30	ns
WRITE CYC	CLE	<u></u>	1							1	
TWLWL	tWC	Write cycle time	50	_	55	-	65		70		ns
TWLWH	tWPW	Write pulse width (19)	40	_	45		50		55		ns
TWHWL	tWR	Write recovery time	10		10	_	15		15		ns
TDVWH	tDS	Data set-up time	20		20	-	30		30		ns
TWHDX	tDH	Data hold time	0	_	0	_	0		0	T	ns
RESET CYC	CLE									1	
TRSLWL	tRSC	Reset cycle time	50		55		65		70		ns
TRSLRSH	ıRS	Reset pulse width (19)	40	_	45	1	50	T -	55		ns
TWHRSH	tRSS	Reset set-up time	40	_	45	 -	50		55	T -	ns
TRSHWL	tRSR	Reset recovery time	10	-	10	 	15	-	15	_	ns
RETRANSM	IIT CYCLE	L		 				†			
TRTLWL	tRTC	Retransmit cycle time	50	-	55	_	65	_	70	_	ns
TRTLRTH	tRT	Retransmit pulse width (19)	40	-	45	-	50		55	-	ns
TWHRTH	tRTS	Retransmit set-up time (20)	40	-	45		50		55	T -	ns
TRTHWL	tRTR	Retransmit recovery time	10	_	10	-	15		15	_	ns
FLAGS	,	1						1		†	1
TRSLEFL	tEFL	Reset to EF low		50	-	55	-	60		65	ns
TRSLFFH	tHFH, tFFH	Reset to HF/FF high	T -	50	-	55	-	60	_	65	ns
TRLEFL	tREF	Read low to EF low	†	30	_	40	-	45	_	50	ns
TRHFFH	tRFF	Read high to FF high	-	35	_	40	_	45	<u> </u>	50	ns
TEFHRH	tRPE	Read width after EF high	4()	-	45	†	50	-	55		ns
TWHEFH	tWEF	Write high to EF high	<u> </u>	35		40	-	45		50	ns
TWLFFL	tWFF	Write low to FF low	†	35	1 -	40	_	45		50	ns
TWLHFL	tWHF	Write low to HF low	<u> </u>	50	-	55	-	60		65	ns
TRHHFH	tRHF	Read high to HF high		50	_	55	-	60		65	ns
TFFHWH	tWPF	Write width after FF high	40		45	1 -	50		55	-	ns

	SYMBOL (17)	PARAMETER (18) (22)	M 67281A/287A COM, IND, MIL, AUTO - 20		M 67201A/202A COM, IND, MIL, AUTO – 25		M 67201A/202A MEL ONLY - 30		M 67281A/282A COM, IND, AUTO -35		UNIT
			MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
EXPANSIO!	N		PRE	VIEW							
TWLXOL	tXOL	Read/Write to XO low	-	20	-	25		30	-	35	ns
TWHXOH	tXOH	Read/Write to XO high		20	-	25	-	30	-	35	ns
TXILXIH	tXI	XI pulse width	20		25		30	-	35	-	ns
TXIHXIL	tXIR	XI recovery time	10	-	10		10	_	10	T-	ns
TXILRL	tXlS	XI set-up time	10	-	10		10	-	10	-	ns

SYMBOL (16)	SYMBOL (17)	PARAMETER (18) (22)	M 67201A/202A MIL ONLY - 46		M 67201A/202A COM, IND, MIL, AUTO – 45		MIL ONLY		M 67201A/202A COM, IND, AUTO -55		UNIT
			MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
EXPANSIO	N										
TWLXOL	IXOL	Read/Write to XO low	-	40	-	45		50	_	55	ns
TWHXOH	tXOH	Read/Write to XO high	-	40	-	45		50	-	55	ns
TXILXIH	1X)	XI pulse width	40		45	_	50	-	55		ns
TXIHXIL	tXIR	XI recovery time	10	_	10	Ī -	10	-	10		ns
TXILRL	tXIS	X1 set-up time	10		10		15		15	_	ns

Notes: 16. STD symbol.

- 17. ALT symbol.
- 18. Timings referenced as in ac test conditions.
- 19. Pulse widths less than minimam value are not allowed.
- 20. Values guaranteed by design, not currently tested.
- 21. Only applies to read data flow-through mode.
- 22. All parameters tested only.

Figure 8. Asynchronous Write and Read Operation.

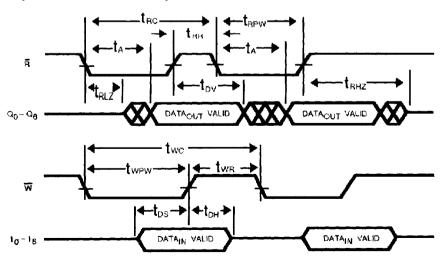




Figure 9. Full Flag from Last Write to First Read.

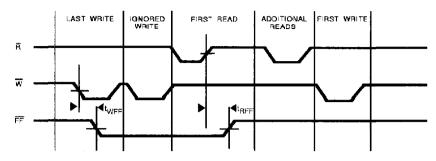


Figure 10. Empty Flag from Last Read to First Write.

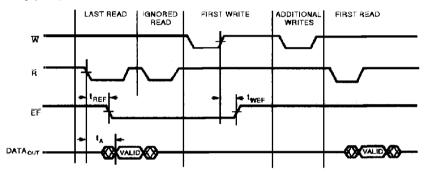
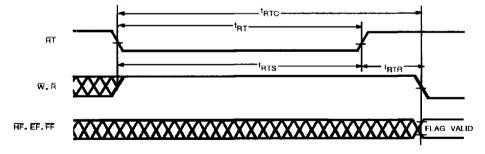


Figure 11. Retransmit.



Note: 23. \overline{EF} , \overline{FF} and \overline{HF} may change status during Retransmit, but flags will be valid at t_{RTC} .

Figure 12. Empty Flag Timing

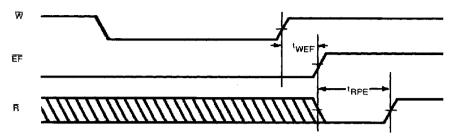


Figure 13. Full Flag Timing

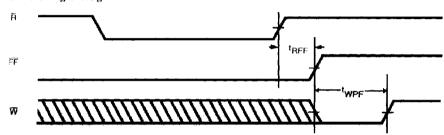


Figure 14. Half-Full Flag Timing.

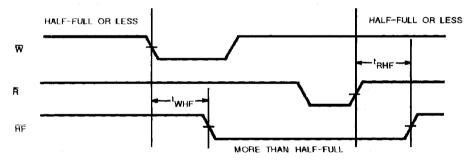




Figure 15. Expansion Out.

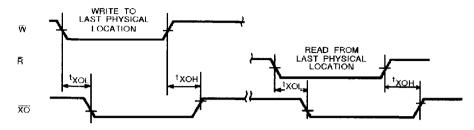


Figure 16. Expansion In.

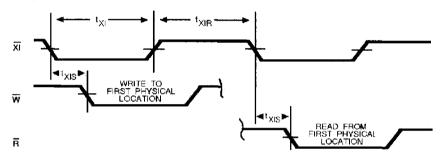


Figure 17. Read Data Flow - Through Mode.

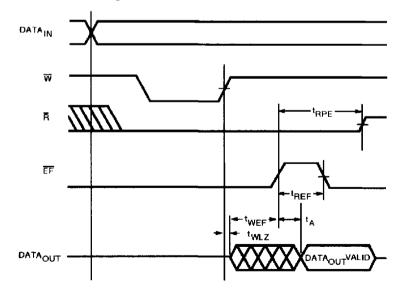
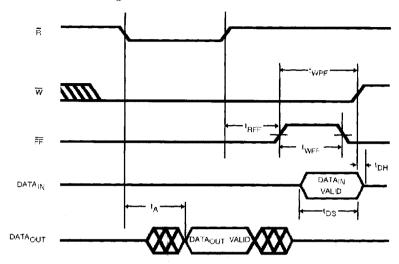


Figure 18. Write Data Flow - Through Mode.



Ordering Information

TEMPERATURE RANGE	PACKAGE	DEVICE :	SPEED	FLOW	
3P = 28 pi *TI = 28 p *UI = 28 p 4J = 32 pi SI = 32 pi DP = 28 p	in FP 400 mils (Preview) brazed 28 pins 300 mils orm 67201 = 5 67202 = 1 9°C 67202 = 1 25°C AU = Lov AV = Very	512×9 FIFO 1024×9 FIFO	20 ns 25 ns 30 ns 35 ns 40 ns 45 ns 50 ns 55 ns	/883 P883 SB/SC SHXXX FHXXX EHXXX MHXXX LHXXX : R	= MHS standards = MIL STD 883 Class B or S = MIL STD 883 + PIND test = SCC 9000 level B/C = Special customer request = Flight models (space) = Engineering models (space) = Mechanical parts (space) = Life test parts (space) = Tape and reel = Tape and reel dry pack = Dry pack

^{*} On request only



Military and Space Versions

The following tables give package/consumption/access time/process flow available combinations

Temp. range		Consumption		Access Time (ns)				Std process 67201A	RT process 67201F	
		V	L	25	30	40	50	Mil flows (including SMD5962-87531 SMD5962-89863)	Mil flows	Space flows
M IP	IP	ı	•	х	•	•	•	•		.1
	4J	1	•	X	•	•	•	•		
	CP	1	•	X	•	•	•	•		
	DP	1	•	X	x	X	X	x		
	0	X	•	Х	х	Х	•	•		
S	4J	1		х	•	•	•		•	•
	CP	1		X	•	•	•		•	•
	DP	1		X	x	X	X		X	X
	0	X	•	X	X	x	•		•	•

Temp. range	Packages	Consumption		Access Time (ns)				Std process 67202A	RT process 67202F	
		v	L	25	30	40	50	Mil flows (including SMD5962–89536)	Mil flows	Space flows (including SCC9301032)
M IP	1P	•	•	Х	•	•	•	•		
	43	•	•	X	•	•	•	•		
	CP	•	•	X	•	•	•	•		
	DP	•	•	X	X	X	X	X		į.
	0	Х	•	X	Х	X	•	•		
S 4J	4J	•		х	•	•	•		•	•
	CP	•		X	•	•	•		•	•
	DP	•		X	X	X	X		X	X
	0	X	•	X	X	Х	•		•	•

• = product in production

X = call sales office for availability

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